NxH3670 Wireless Gaming Headset Solution





NxH3670 Value proposition

Applications

Wireless gaming / communication headsets: small form factor communication and consumer gaming headsets with long battery life

Power efficient

Lowest active energy consumption in the market Average power consumption of <8.5mW for 48kHz audio

Highly integrated

Low external component count enabling miniaturized devices

HiFi Audio

Optimized architecture with DSP and hardware support for robust, high quality audio streaming at <20ms latency

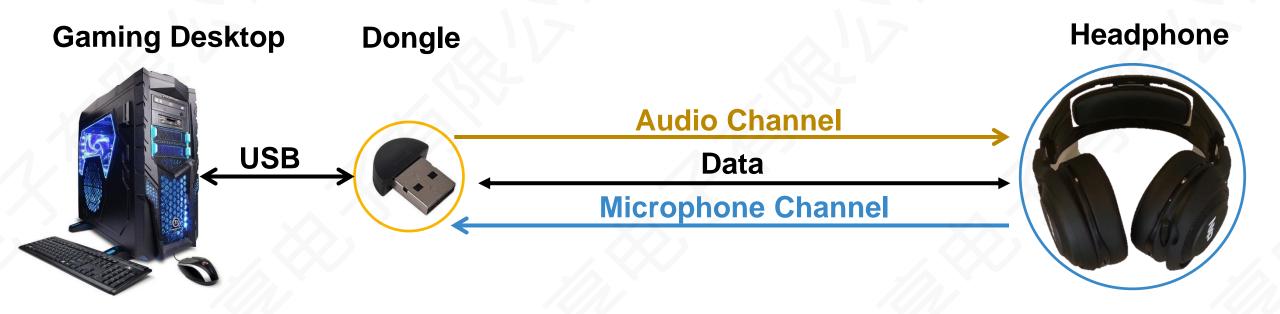
Flexible

Bluetooth Low Energy 5.0 certified.

Proprietary low latency audio streaming support



NxH3670 Wireless Headset Use Case



Data channel

- HCI interface
- ~4kbps

Forward audio channel

- Stereo audio
- SBC HQ audio codec
- 48kHz, 16 bit
- Latency < 20ms

Microphone channel

- Mono audio
- G.722 audio codec
- 16kHz, 16 bit



NxH3670 Features 1/3

Fully integrated 2.4GHz RF Transceiver

- PHY + MAC + Higher network layers
- Supports BLE 1 & 2Mbps mode
- TX output power of -10dBm to +4dBm
- RX sensitivity of
 - -94 dBm in BLE 1Mbps mode
 - -90 dBm in BLE 2Mbps mode
- Supports 16MHz and 32MHz XTAL

Multi-standard PHY and Link Layer

- Bluetooth Low Energy 5.0 certified
- Proprietary isochronous audio streaming protocol

Industry-lowest Power RF Transceiver

- Continuous RX 4mA @ 1.2V
- Continuous TX (0dBm) 7mA @ 1.2V

NxH3x70 MCU Peripherals Security **PMU** (I2C, UART, timers, (RSA, AES, M/S SPI, GPIO) SHA) BLE 5.0 Radio & MAC Cortex M0 **Audio Processing Accelerators** CoolFlux **DSP** (adaptive SRC, ADPCM/G722 codecs.



latency control.

12S/PCM interface)

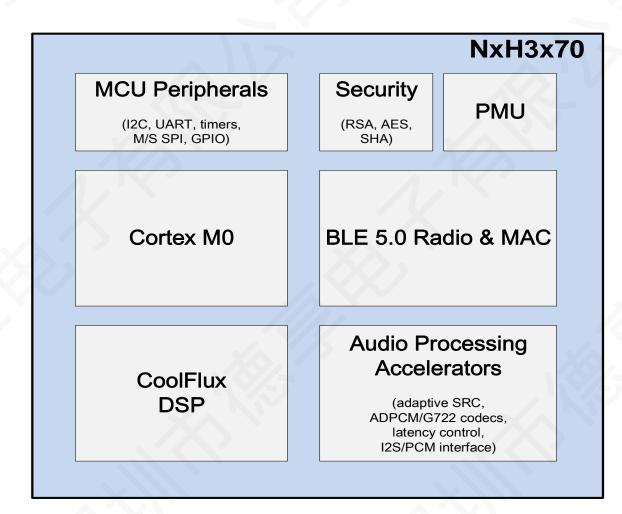
NxH3670 Features 2/3

Cortex M0 MCU

- Runs BLE higher layers and audio profiles
- 3/4 wire slave SPI
- 3/4 wire master SPI
- I2C master
- UART
- SWD

Flexible Audio Path

- Optimized HW-accelerated audio datapath
- Sample frequency: 16 ...48kHz
- CoolFlux DSP
- G722/SBC audio compression codec
- I2S or PCM interface to Host and codecs





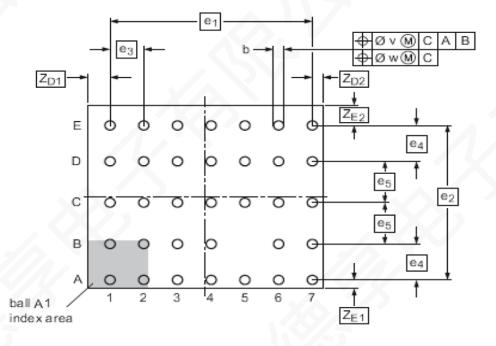
NXH3670 Features 3/3

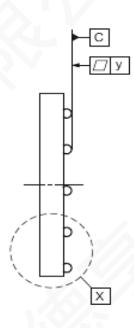
Highly Integrated

- On-chip supply regulators
- Limited external components

Package

- Flexible IO Switch Matrix with configurable IO voltage up to 2.6V
- Bump pitch of 400 um with ball diameter 130um
- 34 bump package: 7 by 5 bump grid
- WLCSP ~ 7.25 mm2









NxH3670 SDK Board

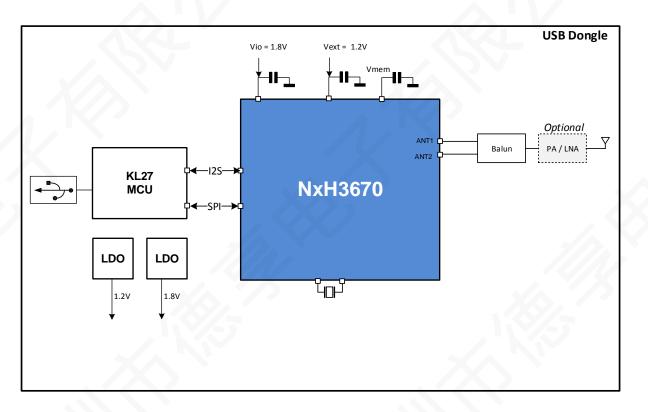
NxH3670 development board

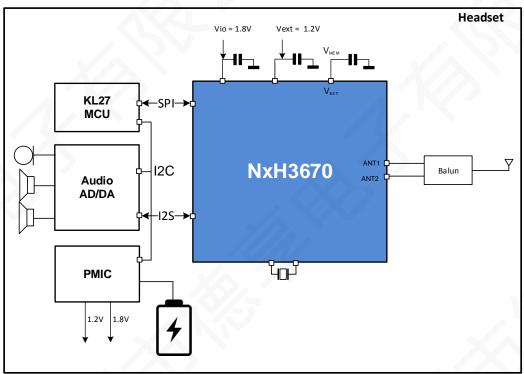
- Flexible board intended for SW and system development, debug and bring-up
- Contains
 - NxH3670
 - KL27 Microcontroller
 - Audio codec
 - Power management
 - Battery
- Full signal observability
- Reconfigurable as both dongle as well as headset
- Planning:
 - Available in SampleStore





NxH3670 Reference Design – Gaming Headset







NxH3670 ADK Reference Design

NxH3670 application development board

- Contains both dongle as well as headset reference design
- Form factor reference showing real life performance of the full NxH3670 AoBLE solution

Dongle

- NxH3670
- KL27 MCU
- Integrated PCB antenna

Headset

- NxH3670
- KL27 MCU
- Dialog codec
- Integrated omni-directional PCB antenna

Planning:

Available in SampleStore









SECURE CONNECTIONS FOR A SMARTER WORLD